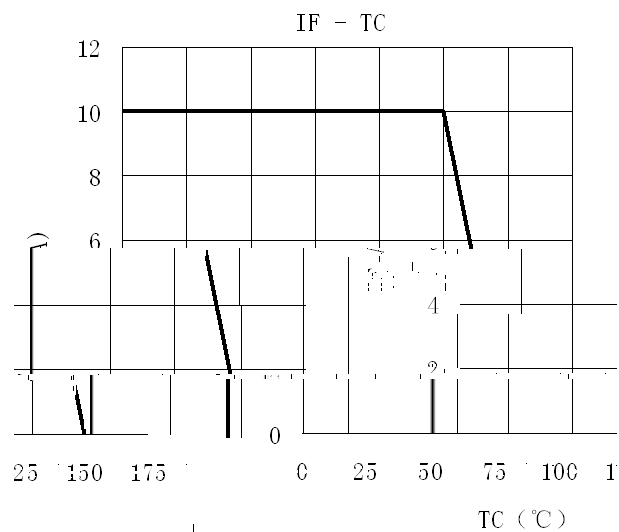
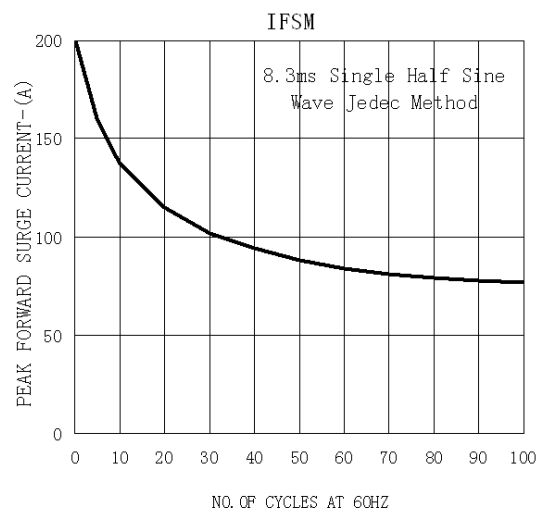
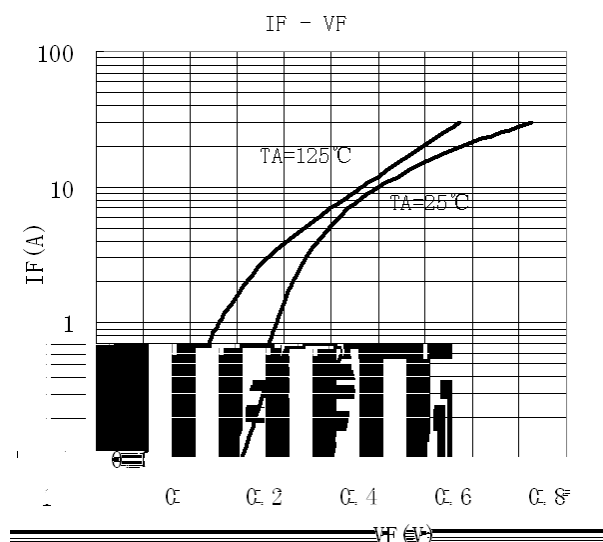
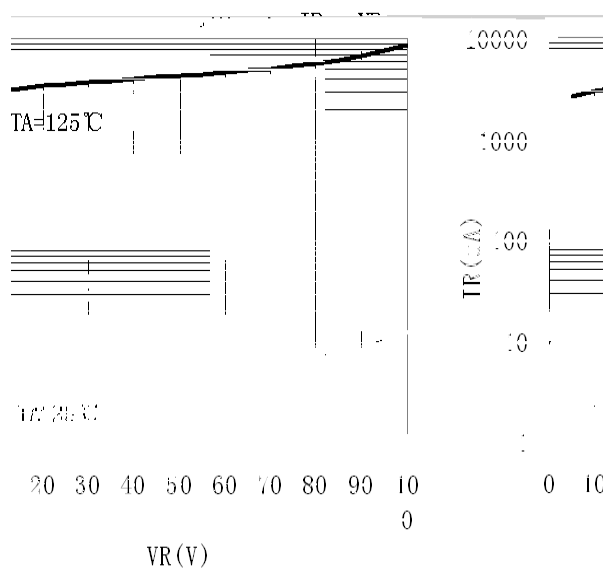
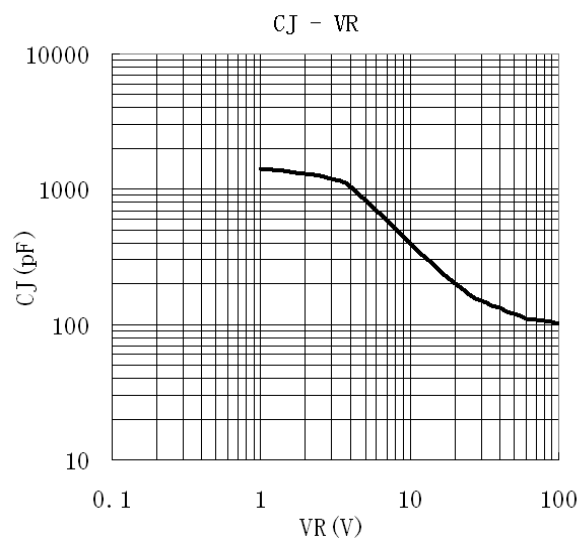


		0	/W
	1/W		
Junction and Storage Temperature Range	T _j T _{stg}	-55 +150	

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Voltage	V _(BR) R I	R=1mA(Ta=25) 100			V	
Forward Voltage	V _F	I _F =2A(Ta=25)		0.41	0.45	V
		I _F =10A(Ta=25)	0.58	0.65	V	
		I _F =2A(Ta=125)	0.31	0.40	V	
		I _F =10A(Ta=125)	0.55	0.65	V	
Instantaneous Reverse Current	I _R Note 2	V _R =100V(Ta=125)				

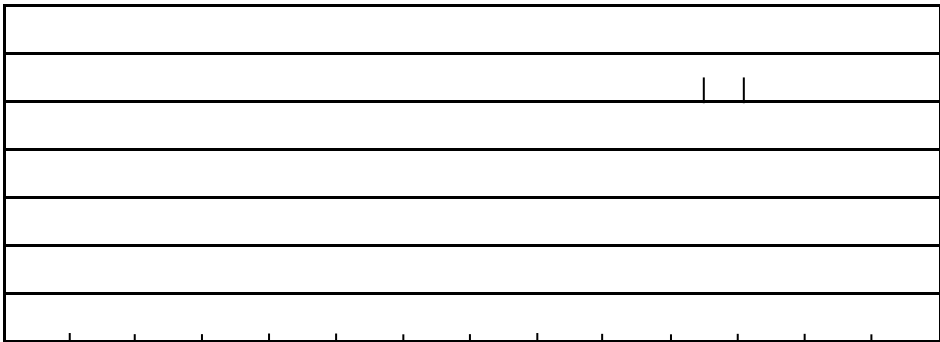
/ Electrical Characteristic Curve



/ Package Dimensions



() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- 1

150 180

60 90sec;

1.Preheating:150~180 , Time:60~90sec.
- 2

245 5

5 0.5sec;

2.Peak Temp.:245 5 , Duration:5 0.5sec.
- 3

2 10

/sec.

3. Cooling Speed: 2~10 /sec.

/ Resistance to Soldering Heat Test Conditions

260 5 10 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box
TO-277	5,000	3	15,000	6	90,000	13 ×12	360×360×50	380×335×366

/ Notices